



# S1125 无卤普通Tg补强板

S1125 Halogen-free normal Tg stiffer

## 特点

- 不含卤素, Dicy 固化 普通Tg
- 不含锑、红磷等成分
- 优异的表面粘结性

## FEATURES

- Halogen free, dicy cured systems, normal Tg;
- Free of constituents such as antimony, red phosphorous etc..
- Good adhesion to the surface.

## 应用领域

手机、电脑、仪器仪表、摄录机、通讯设备等

## APPLICATIONS

Mobile phone, Computer, instrumentation, VCR, communication equipment etc..

## 性能表 GENERAL PROPERTIES

项目 Items	条件 Condition	单位 Unit	性能数据 Property Data	
			Spec	Typical Value
玻璃化转变温度 Tg	DSC	°C	≥125	130
阻燃性 Flammability	C-48/23/50 and E-24/125	Rating	V-0	V-0
耐热性 Thermal Stress	288°C, solder dip	-	>10s No Delamination	>100s No Delamination
表面粘结性 Surface Adhesion	A	N/mm	>1.5	2.2
弯曲强度 Flexural Strength	LW	Mpa	≥415	580
	CW		≥345	450
吸水率 Water Absorption	D-24/23	%	≤0.5	0.10
Z轴热膨胀系数 CTE(Z-axis)	Before Tg	PPM/°C	≤60	40
	After Tg	PPM/°C	≤300	235
	50-260°C	%	≤3.5	3.0
热分解温度 Td	Wt5%loss	°C	≥325	350
260°C爆板时间 T260	TMA	min	≥30	60
288°C爆板时间 T288	TMA	min	≥5	30

注1: 以上性能数据基于S1125 0.30mm样品测试结果

注2: 表面粘结性测试方法为将电解铜箔(1Oz)、SF305B(胶膜)、S1125叠合, 在170°C、200PSI的参数下热压40min, 再测试90°剥离强度。

Remark:1: Performance data based on the sample S1125 0.30mm test results

2: The test method of PS: superposition the ED copper foil(1Oz), bonding film, S1125, then laminate them, using the parameters 170°C、200PSI, 40 minutes. Using 90 degree angle peeling.



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FPC加工建议PROCESSING SUGGESTIONS

### 开料 SHAPE CUTTING

如需开料，推荐选用锯床方式，其次剪床。

If you need shape cutting, recommended to choose sawing machine, secondly shears.

### 清洗 CLEAN

S1125板材表面完全不含硅类离型剂，只需经过简单的水洗即可。可根据实际使用情况，选择刷板或磨板的方式进一步提高板面粗糙度。

There is no Silicon class mold release agent on S1125 surface. Only need wash by water. According to the actual situation, you can choose brushing or friction to improve the roughness.

### 背胶 BACK GLUE

推荐使用过塑机过塑热固胶的方式，也可使用复合机压合压敏胶进行背胶

Recommended used plastic molding machine a thermosetting adhesive, also can use compound machine pressing pressure sensitive adhesive for lamination.

### 分切 CUTTING

使用剪床分切。堆叠数量偏多可能会引起分切后出现板边分层和毛边问题，可根据实际使用情况适当减少堆叠数量。

Using the shear cutting. According to actual situation appropriate reduce the amount of stack, otherwise layering and burrs problem may come up.

### 外形 OUT SHAPE

使用厚度 $>0.40\text{mm}$ 的S1125板材作补强，其冲外形的冲切压力可适当提高，并加强刀口的清洁频次，以避免冲切边的分层问题。

When the thickness over  $0.40\text{mm}$ , you should improve the die-cut pressure and the blade cleaning frequency.

### 储存条件 STORAGE CONDITION

存放在通风、干燥、室温的环境下，避免阳光直射、雨淋，避免腐蚀性气体的侵蚀（存放的环境直接影响产品的品质）。在以上合适的环境下可存放一年，其内部性能可以满足IPC4101C/92标准要求。

Stored in ventilated, dry and at room temperature environment, avoid direct sunlight, rain, prevent erosion of corrosive gas (The environment affect the quality of the product)。Fit the environment can deposit one year. The internal performance meet the requirements of IPC4101C/92.